

Shenzhen Pancun Technology Co.,Ltd.

Industrial mSATA Drive

Product DataSheet



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Revision History

Revision	Draft Date	History	Author
1.0	2022/8/16	New release	Golden Lee
1.1	2023/3/29	Removed safety certification	Golden Lee
1.2	2023/6/13	1. Added pSLC 512GB support 2. Added OPAL support	Golden Lee
1.3	2023/8/23	Added Extend grade: -25°C ~ 85°C series	Golden Lee

Product Overview

● Capacity ▪ TLC: 64GB up to 2TB ▪ pSLC: 32GB up to 512GB ● SATA Interface ▪ SATA Revision 3.2 ▪ SATA Gen3/Gen2/Gen1 interface ● Performance ▪ Read up to 550 MB/s ▪ Write up to 510 MB/s ● Power Consumption^{Note1} ▪ Active mode: < 1,750 mW ▪ Idle mode: < 210 mW ● Reliability^{Note2} ▪ MTBF > 2,500,000 hours ▪ UBER < 1 sector per 10¹⁶ bits ▪ TBW^{Note3}: ➢ TLC: up to 2,900 TB ➢ pSLC: up to 25,800 TB ● Low Power Management ▪ DEVSLP Mode (Optional) ● ECC ▪ LDPC / RAID ECC ▪ Low density parity check code (>120buit/KBytes)	● Temperature Range^{Note4} ▪ Operation Temperature: ➢ Standard grade: 0°C ~ 70°C ➢ Wide grade: -40°C ~ 85°C ➢ Extend grade: -25°C ~ 85°C ▪ Storage Temperature: ➢ -40°C ~ 85°C ● RoHS Compliant ● EMI Compliant ▪ EN55032, CISPR 32 (CE) ▪ ANSI C63.4 (FCC) ▪ CNS 13438 (BSMI) ▪ VCCI-CISPR 32 (VCCI) ● Special Features & Flash Management ▪ Advanced Wear Leveling ▪ Bad Block Management ▪ TRIM ▪ SMART ▪ Over-Provision ▪ SmartZIP™ ▪ TCG Pyrite/OPAL
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Notes:

1. Please refer to “4.2 Power Consumption” for details.
2. Please refer to “Environmental Specifications” in chapter 3 for details.
3. Please refer to “2.4 TBW & DWPD” for details.
4. The operation temperature means the case temperature (T_c), in which can be detected via the SMART.

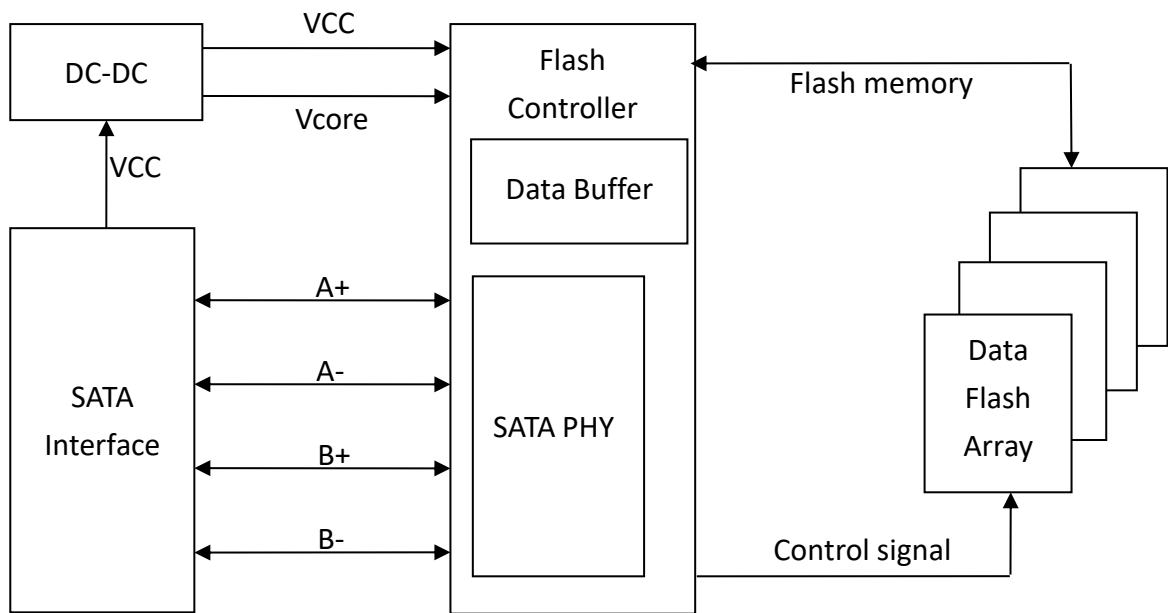
1. INTRODUCTION



1.1. General Description

Pancun's mSATA delivers all the advantages of flash disk technology with the Serial ATA I/II/III interface and is fully compliant with the standard mSATA form factor, known as JEDEC MO-300 standard. With maximum performance reaching 550MB/s read, 510MB/s write, and wide range of capacities up to 2TB, making it the best embedded solution for new platforms.

1.2. Block Diagram



mSATA Block Diagram

2. PRODUCT SPECIFICATIONS



2.1. Product Specifications

- **Capacity**
 - TLC: From 64GB up to 2TB
 - pSLC: From 32GB up to 512GB
- **Electrical/Physical Interface**
 - SATA Interface
 - Compatible with SATA 1.5Gbps, 3Gbps and 6Gbps interface
 - AC coupling for transmitter and receiver
 - Self-calibrated and embedded termination resistor at transmitter
 - Support expanded register for SATA protocol 48 bits addressing mode
 - Support power management
- **Supported NAND Flash**
 - Kioxia BiCS5 3D-TLC, Toggle 3.0
- **ECC Scheme**
 - Applies the LDPC (Low Density Parity Check) of ECC algorithm
- **Operation Voltage Supply**
 - $3.3V \pm 5\%$
- **Power Saving Implementation**
 - Idle mode
 - Partial mode
 - Slumber mode
- **LBA Range**
 - IDEMA standard
- **UART / GPIO function**
- **Support SMART and TRIM commands**
- **Certification & Compliance**
 - RoHS
 - WHQL

2.2. Device Capacity

Capacity	IDEMA Standard		User Data Size
	512Bytes/Sector	4KBytes/Sector	
	Total Sectors (LBA)	Total Sectors (LBA)	
32GB	62,533,296	7,816,662	Depended on file management
60GB	117,231,408	14,653,926	
64GB	125,045,424	15,630,678	
120GB	234,441,648	29,305,206	
128GB	250,069,680	31,258,710	
240GB	468,862,128	58,607,766	
256GB	500,118,192	62,514,774	
480GB	937,703,088	117,212,886	
512GB	1,000,215,216	125,026,902	
960GB	1,875,385,008	234,423,126	
1TB	2,000,409,264	250,051,158	
1920GB	3,750,748,848	468,843,606	
2TB	4,000,797,360	500,099,670	

Notes:

1. 1 Gigabyte (GB) is equal to 1,000,000,000 Bytes; 1 sector is equal to 512 Bytes.
2. The calculation is following IDEMA Standard.
3. The total actual user data size of the SSD may be less than device capacity due to SSD format, SSD partition, operating system.
EX: OS shows 223.57GB (NTFS) with 240GB SSD.

2.3. Performance

Capacity	Flash Structure	Sequential (MB/s)		4K Random (IOPS)	
		Read	Write	Read	Write
60GB/64GB	64GB x 1, BiCS5 TLC, BGA	380	265	36,500	57,500
120GB/128GB	64GB x 2, BiCS5 TLC, BGA	550	450	44,500	78,500
240GB/256GB	128GB x 2, BiCS5 TLC, BGA	550	485	75,500	82,500
480GB/512GB	256GB x 2, BiCS5 TLC, BGA	550	500	91,500	83,500
960GB/1TB	256GB x 4, BiCS5 TLC, BGA	550	510	96,000	85,500
1920GB/2TB	512GB x 4, BiCS5 TLC, BGA	550	510	93,500	85,000
32GB	64GB x 2, BiCS5 pSLC, BGA	540	465	49,500	78,500
64GB	128GB x 2, BiCS5 pSLC, BGA	550	485	85,500	84,500
128GB	256GB x 2, BiCS5 pSLC, BGA	550	500	96,000	86,000
256GB	256GB x 4, BiCS5 pSLC, BGA	550	510	97,500	87,500
512GB	512GB x 4, BiCS5 pSLC, BGA	550	510	97,000	86,500

Notes:

- Performance may differ according to flash configuration and platform.
- The table above is for reference only.
- Performance is measured with the follow conditions
 - CrystalDiskMark 6.0, 1GB range, QD32T1 for sequential
 - IOmeter, QD32T8, 1GB range for 4K Random
 - Windows 10 professional (x64), Version 1809
- Measurement environment: Room temperature: 20~25℃, humidity: 40~60%RH, DC+3.3V condition.

2.4. TBW (TeraBytes Written) and DDPD (Drive Write Per Day)

Capacity	Flash Type	TBW	DDPD
60GB/64GB	TLC	65	0.92
120GB/128GB	TLC	90	0.64
240GB/256GB	TLC	220	0.78
480GB/512GB	TLC	540	0.96
960GB/1TB	TLC	1,200	1.07
1920GB/2TB	TLC	3,000	1.29
32GB	pSLC	1,000	28.53
64GB	pSLC	3,000	42.81
128GB	pSLC	6,400	45.66
256GB	pSLC	13,000	46.37
512GB	pSLC	25,800	46.01

Notes:

1. TBW is measured by JEDEC 219A Client workload.
2. TBW may differ according to flash configuration, platform and data written.
3. DDPD is calculated based on 3-year lifetime.
4. DDPD (Drive Write Per Day) = $TBW / [365 \times \text{years} \times \text{User Capacity(TB)}]$
5. The endurance of SSD could be estimated based on user behavior, NAND endurance cycles, and write amplification factor. It is not guaranteed by flash vendor.

2.5. POR/SPOR Standby Ready Time

● POR/SPOR Ready Time

Capacity	POR ready time				SPOR ready time			
	Power On		Identify		Power On		Identify	
	Typ.	Max.	Typ.	Max.	Typ.	Max.	Typ.	Max.
60GB/64GB	300	500	350	550	5,000	9,000	5,100	9,100
120GB/128GB					5,000		5,100	
240GB/256GB					8,000		8,100	
480GB/512GB					8,000		8,100	
960GB/1TB					8,000		8,100	
1920GB/2TB					8,000		8,100	
32GB					5,000		5,100	
64GB					8,000		8,100	
128GB					8,000		8,100	
256GB					8,000		8,100	
512GB					8,000		8,100	

Unit: ms

Notes:

- POR/SPOR stands for following:
 - POR (Power On Ready): The ready time variation depends on data recover size.
 - SPOR (Power On Ready after Sudden Power Off): The ready time variation depends on data recover size.
- Power On/Identify ready time stands for following:
 - Power on Time: From Power On to SSD response after drive ready.
 - Identify Time: Power on Time + host issue Identify Command, response Ack.
- Measurement environment: Room temperature: 20~25℃, humidity: 40~60%RH, DC+3.3V condition.

2.6. TCG Opal 2.0

The Opal specification is a set of specifications for self-encrypting drives published by the Trusted Computing Group (TCG), a non-profit organization that develops, defines, and promotes standards and specifications for secure computing. The Opal Security Subsystem Class(SSC) 2.0 defines the details of data management in storage devices and the classes authority for data access, and secures data from theft and tampering by unauthorized persons who are able to gain access to the storage device or host system.

TCG Opal 2.0 Main Features:

- AES 256-bit Hardware Self Encryption
- Deploy Storage Device & Take Ownership:
The Storage Device is integrated into its target system and ownership transferred by setting or changing the Storage Device's owner credential.
- Activate or Enroll Storage Device:
LBA ranges are configured and data encryption and access control credentials (re)generated and/or set on the Storage Device. Access control is configured for LBA range unlocking.
- Lock & Unlock Storage Device:
Unlocking of one or more LBA ranges by the host and locking of those ranges under host control via either an explicit lock or implicit lock triggered by a reset event. MBR shadowing provides a mechanism to boot into a secure pre-boot authentication environment to handle device unlocking.
- Repurpose & End-of-Life:
Erasure of data within one or more.
- Physical Presence SID (PSID):
PSID is defined by TCG OPAL as a 32-character string and the purpose is to revert SSD back to its manufacturing setting when the drive is still OPAL-activated. PSID code can be printed on a SSD label when an OPAL-activated SSD supports PSID revert feature.

3. ENVIRONMENTAL SPECIFICATIONS



3.1. Environmental Conditions

3.1.1. Temperature Specification

	Mode	Min.	Max.	Unit
Temperature Ranges	Operation (Standard)	0	70	°C
	Operation (Wide)	-40	85	°C
	Storage	-40	85	°C
Humidity (non- condensing)	Operation	5	90	%
	Storage	5	93	%
Temperature Cycle Test	Operation (Standard)	0	70	°C
	Operation (Wide)	-40	85	°C
	Storage	-40	85	°C

Notes:

1. The operation temperature means the case temperature, in which can be detected via the S.M.A.R.T. Airflow is suggested and it will allow device to be operated at appropriate temperature for each component during heavy workloads environment.

3.1.2. High Temperature Test Condition

		Temperature	Humidity	Test Time
Operation	Standard Temperature	70°C	0% RH	72 hours
	Wide Temperature	85°C		
Storage	Standard Temperature	85°C	0% RH	168 hours
	Wide Temperature			

Test Reference: IEC 60068-2-2

3.1.3. Low Temperature Test Condition

		Temperature	Humidity	Test Time
Operation	Standard Temperature	0°C	0% RH	72 hours
	Wide Temperature	-40°C		
Storage	Standard Temperature	-40°C	0% RH	168 hours
	Wide Temperature			

Test Reference: IEC 60068-2-1

3.1.4. High Humidity Test Condition

		Temperature	Humidity	Test Time
Operation	Standard Temperature	40°C	90% RH	72 hours
	Wide Temperature	55°C		
Storage	Standard Temperature	40°C	93% RH	96 hours
	Wide Temperature	55°C		

Test Reference: IEC 60068-2-3

3.1.5. Temperature Cycle Test

		Temperature	Humidity	Test Time
Operation	Standard Temperature	0°C	30 min	20 Cycles
		70°C		
	Wide Temperature	-40°C	30 min	20 Cycles
		85°C		
Storage	Standard Temperature	-40°C	30 min	30 Cycles
		85°C		
	Wide Temperature	-40°C	30 min	50 Cycles
		85°C		

Test Reference: IEC 60068-2-14

3.1.6. Mechanical Specification

Items			Condition
Shock	Non-operational	Acceleration Force	1500G 0-p with half sine wave (0.5ms)
Vibration	Non-operational	Frequency/Displacement	20Hz~80Hz/1.52mm
		Frequency/Acceleration	80Hz~2000Hz/20G p-p with sine wave
Drop	Non-operational	Height of Drop	80cm free fall
		Number of Drop	6 face of each unit
		Conflicting Material	Concrete floor

3.1.7. Electrostatic Discharge (ESD)

Specification	± 4KV
EN 55024	± 4KV each 25 times, 1 second for 1 time. - Contact discharge. - Device functions are affected, EUT will be back to normal state.
CISPR 24	
EN 61000-4-2	
IEC 61000-4-2	

3.1.8. EMI Compliance

Specification

CE: EN 55032, CISPR 32

FCC: ANSI C63.4

VCCI: VCCI-CISPR 32

BSMI: CNS 13438

3.2. Package Qualification

3.2.1. High Temperature Storage Life Test (HTSL)

Parameter	Test Condition	
Storage	Temperature	Test Duration
	150°C	168/1000 hours

Test Reference: JESD22 A103

3.2.2. Solderability Test

Parameter	Test Condition
Storage	85°C/85% RH 16 hours, bake 1 hour at 125°C. - Molten solder temperature: 245±5°C - Dwell time: 5 seconds

Note: Spec: > 95% of coating area, pinhole, voids, do not exceed 5% of total area.

3.2.3. Pre-condition Test

Parameter	Test Method	Test Condition
Storage	JESD22-A113	- Temperature Cycle (-65°C/150°C, 5 cycles) - Baking (125°C, 24 hours) - Temp & Humidity Soaking (30°C/60% RH, 192 hours) - IR Reflow 3 cycles

Note: The parts passing this test will be used to do HAST and TCT.

3.2.4. High Acceleration Stress Test (HAST/unbias)

Parameter	Test Method	Test Condition		
		Ambient Temperature	Ambient Humidity	Test Duration
Storage	JESD22-A110	130°C	85% RH	96 hours

3.2.5. Temperature Cycling Test (TCT)

Parameter	Test Method	Test Condition		
		High Temperature	Low Humidity	Test Duration
Storage	JESD22-A104	150°C	-65% RH	200/500 cycles

3.3. UBER

Capacity	UBER
32GB ~ 2TB	< 1 sector per 10^{16} bits read

Notes:

1. UBER (Uncorrectable Bit Error Rates) means the uncorrectable error per bits read.
2. $UBER = FER \text{ (fail rate)} / \text{Data Size (user data bit)}$.
3. $FER = \text{uncorrectable ECC frame number} / \text{total ECC frame number}$.
4. The LDPC capability > 120bit/KB.

3.4. MTBF

MTBF, an acronym for Mean Time between Failures, is a measure of reliability of a device. Its value represents the average time between a repair and the next failure. The unit of MTBF is in hours. The higher the MTBF value, the higher the reliability of the device.

Our MTBF result is based on simulation software (Relax 7.3). Please note that a lower MTBF should be expected for higher capacity drives, and we apply the lowest MTBF for all capacities.

Capacity	MTBF
32GB ~ 2TB	> 2.5 million hours

4. ELECTRICAL SPECIFICATIONS



4.1. Supply Voltage

Parameter	Rating
Operating Voltage	3.3V $\pm$ 5%
Rise Time (Max/Min)	100ms / 0.1ms
Fall Time (Max/Min)	5s / 10ms
Min. Off Time	1s

Notes:

1. Minimum time between power removed from SSD ($V_{cc} < 100$ mV) and power re-applied to the drive.
2. Ensure the voltage of each power domain in SSD has enough time to discharge less than 0.1V.
3. Rise Time during from 10% to 90% of 3.3V.
4. Fall Time during from 90% to 10% of 3.3V.

4.2. Power Consumption

Capacity	Flash Structure	Read	Write	Partial	Slumber	Idle
64GB	64GB x 1, BiCS5 TLC, BGA	970	900	65	25	210
128GB	64GB x 2, BiCS5 TLC, BGA	1,150	1,250	65	25	210
256GB	128GB x 2, BiCS5 TLC, BGA	1,150	1,350	65	25	210
512GB	256GB x 2, BiCS5 TLC, BGA	1,250	1,600	65	27	210
1TB	256GB x 4, BiCS5 TLC, BGA	1,350	1,750	65	27	210
2TB	512GB x 4, BiCS5 TLC, BGA	1,450	1,750	65	27	210
32GB	64GB x 2, BiCS5 pSLC, BGA	1,100	1,100	65	25	175
64GB	128GB x 2, BiCS5 pSLC, BGA	1,100	1,150	65	25	175
128GB	256GB x 2, BiCS5 pSLC, BGA	1,150	1,150	65	25	175
256GB	256GB x 4, BiCS5 pSLC, BGA	1,200	1,150	65	25	175
512GB	512GB x 4, BiCS5 pSLC, BGA	1,350	1,300	65	25	175

Unit: mW

Notes:

1. It's average value of power consumption is achieved based on 100% conversion efficiency.
2. Sequential R/W is measured while testing 4000MB sequential R/W 5 times by CrystalDiskMark.
3. Power Consumption may differ according to flash configuration and platform.
4. Measurement environment: Room temperature: 20~25°C, humidity: 40~60%RH, DC+3.3V condition.

5. INTERFACE



5.1. Pin Assignment and Descriptions

Pin #	mSATA Pin	Description
1	NC	No Connect
2	+3.3V	3.3V Source
3	NC	No Connect
4	DGND	Digital GND
5	NC	No Connect
6	NC	No Connect
7	NC	No Connect
8	NC	No Connect
9	DGND	Digital GND
10	NC	No Connect
11	NC	No Connect
12	NC	No Connect
13	NC	No Connect
14	NC	No Connect
15	DGND	Digital GND
16	NC	No Connect
17	NC	No Connect
18	DGND	Digital GND
19	NC	No Connect
20	NC	No Connect
21	SATA GND	SATA Ground Return Pin
22	NC	No Connect
23	TXP (out)	Host Receiver Differential Signal Pair
24	+3.3V	3.3V Source
25	TXN (out)	Host Receiver Differential Signal Pair
26	SATA GND	SATA Ground Return Pin
27	SATA GND	SATA Ground Return Pin
28	NC	No Connect
29	SATA GND	SATA Ground Return Pin
30	NC	No Connect
31	RXN (in)	Host Transmitter Differential Signal Pair
32	NC	No Connect
Pin #	mSATA Pin	Description
33	RXP (in)	Host Transmitter Differential Signal Pair
34	DGND	Digital GND

35	SATA GND	SATA Ground Return Pin
36	NC	No Connect
37	SATA GND	SATA Ground Return Pin
38	NC	No Connect
39	+3.3V	3.3V Source
40	DGND	Digital GND
41	+3.3V	3.3V Source
42	NC	No Connect
43	NC	No Connect
44	DEVSLP	Enter/Exit DevSleep
45	NC	Reserved pin
46	NC	No Connect
47	NC	Reserved pin
48	NC	No Connect
49	DAS	Device Activity Signal
50	DGND	Digital GND
51	GND	Default connect to GND
52	+3.3V	3.3V Source

6. SUPPORTED COMMANDS



6.1. ATA Command List

Op-Code	Command Description		Op-Code	Command Description	
00h	NOP		60h	Read FPDMA Queued	
06h	Data Set Management		61h	Write FPDMA Queued	
10h	Recalibrate		70h	Seek	
20h	Read Sectors		90h	Execute Device Diagnostic	
21h	Read Sectors without Retry		91h	Initialize Device Parameters	
24h	Read Sectors EXT		92h	Download Microcode	
25h	Read DMA EXT		93h	Download Microcode DMA	
27h	Read Native Max Address EXT		B0h	SMART	
29h	Read Multiple EXT		B0h	D0h	SMART READ DATA
2Fh	Read Log EXT		B0h	D1h	SMART READ DATA ATTRIBUTE THRESHOLD
30h	Write Sectors		B0h	D2h	SMART ENABLE/DISABLE ATTRIBUTE AUTOSAVE
31h	Write Sectors without Retry		B0h	D3h	SMART SAVE ATTRIBUTE VALUES
34h	Write Sectors EXT		B0h	D4h	SMART EXECUTE OFF-LINE IMMEDIATE
35h	Write DMA EXT		B0h	D5h	SMART READ LOG
37h	Set Native Max Address EXT		B0h	D6h	SMART WRITE LOG
39h	Write Multiple EXT		B0h	D8h	SMART ENABLE OPERATIONS
3Dh	Write DMA FUA EXT		B0h	D9h	SMART DISABLE OPERATIONS
3Fh	Write Long EXT		B0h	DAh	SMART RETURN STATUS
40h	Read Verify Sectors		B0h	DBh	SMART ENABLE/DISABLE AUTOMATIC OFF-LINE
41h	Read Verify Sectors without Retry		B1h	DEVICE CONFIGURATION OVERLAY	
42h	Read Verify Sectors EXT		B1h	C0h	DEVICE CONFIGURATION RESTORE
45h	Write Uncorrectable EXT		B1h	C1h	DEVICE CONFIGURATION FREEZE LOCK
47h	Read Log DMA EXT		B1h	C2h	DEVICE CONFIGURATION IDENTIFY
57h	Write Log DMA EXT		B1h	C3h	DEVICE CONFIGURATION SET
B1h	C4h	DEVICE CONFIGURATION IDENTIFY DMA	ECh	Identify Device	
B1h	C5h	DEVICE CONFIGURATION SET DMA	EFh	Set Features	
C4h	Read Multiple		EFh	02h	Enable 8-bit PIO transfer mode
Op-Code	Command Description		Op-Code	Command Description	
C5h	Write Multiple		EFh	03h	Set transfer mode based on value in

				Count field		
C6h	Set Multiple Mode		EFh	05h		Enable advanced power management
C8h	Read DMA		EFh	10h		Enable use of Serial ATA feature
C9h	Read DMA without Retry		EFh	10h	02h	Enable DMA Setup FIS Auto-Activate optimization
CAh	Write DMA		EFh	10h	03h	Enable Device-initiated interface power state (DIPM) transitions
CBh	Write DMA without Retry		EFh	10h	06h	Enable Software Settings Preservation (SSP)
CEh	Write Multiple FUA EXT		EFh	10h	07h	Enable Device Automatic Partial to Slumber transitions
E0h	Standby Immediate		EFh	10h	09h	Enable Device Sleep
E1h	Idle Immediate		EFh	55h		Disable read look-ahead feature
E2h	Standby		EFh	66h		Disable reverting to power-on defaults
E3h	Idle		EFh	82h		Disable write cache
E4h	Read Buffer		EFh	85h		Disable advanced power management
E5h	Check Power Mode		EFh	90h		Disable use of Serial ATA feature set
E6h	Sleep		EFh	90h	02h	Disable DMA Setup FIS Auto-Activate optimization
E7h	Flush Cache		EFh	90h	03h	Disable Device-initiated interface power state (DIPM) transitions
E8h	Write Buffer		EFh	90h	06h	Disable Software Settings Preservation (SSP)
E9h	Read Buffer DMA		EFh	90h	07h	Disable Device Automatic Partial to Slumber transitions
EAh	Flush Cache EXT		EFh	90h	09h	Disable Device Sleep
EBh		Write Buffer DMA	EFh	AAh		Enable read look-ahead feature
EFh	CCh	Enable reverting to power-on defaults	F4h			Security Erase Unit
F1h		Security Set Password	F5h			Security Freeze Lock
F2h		Security Unlock	F6h			Security Disable Password
F3h		Security Erase Prepare	F8h			Read Native Max Address

6.2. Identify Device Data

The following table details the sector data returned by the IDENTIFY DEVICE command.

Word	F: Fixed V: Variable X: retired/obsolete /reserved	Default Value	Description
0	F	0040h	General configuration bit-significant information
1	X	*1	Obsolete – Number of logical cylinders
2	F	C837h	Specific configuration
3	X	0010h	Obsolete – Number of logical heads (16)
4-5	X	00000000h	Retired
6	X	003Fh	Obsolete – Number of logical sectors per logical track (63)
7-8	X	00000000h	Reserved for assignment by the Compact Flash Association
9	X	0000h	Retired
10-19	V	Varies	Serial number (20 ASCII characters)
20-21	X	0000h	Retired
22	X	0000h	Obsolete
23-26	V	Varies	Firmware revision (8 ASCII characters)
27-46	V	Varies	Model number (xxxxxxxx)
47	F	8010h	7:0- Maximum number of sectors transferred per interrupt on MULTIPLE commands
48	F	4000h	Reserved
49	F	2F00h	Capabilities
50	F	4000h	Capabilities
51-52	X	00000000h	Obsolete
53	F	0007h	Words 88 and 70:64 valid
54	X	*1	Obsolete – Number of logical cylinders
55	X	0010h	Obsolete – Number of logical heads (16)
56	X	003Fh	Obsolete – Number of logical sectors per track (63)
57-58	X	*2	Obsolete – Current capacity in sectors
59	F	0110h	Number of sectors transferred per interrupt on MULTIPLE commands
60-61	V	*3	Maximum number of sector (28bit LBA mode)
Word	F: Fixed V: Variable	Default Value	Description

	X: retired/obsolete /reserved		
62	X	0000h	Obsolete
63	F	0407h	Multi-word DMA modes supported/selected
64	F	0003h	PIO modes supported
65	F	0078h	Minimum Multiword DMA transfer cycle time per word
66	F	0078h	Manufacturer's recommended Multiword DMA transfer cycle time
67	F	0078h	Minimum PIO transfer cycle time without flow control
68	F	0078h	Minimum PIO transfer cycle time with IORDY flow control
69	F	1F00h	Additional Supported
70	X	0000h	Reserved
71-74	X	0h	Reserved for the IDENTIFY PACKET DEVICE command
75	F	001Fh	Queue depth
76	F	C50Eh	Serial SATA capabilities
77	F	0006h	Supported Serial ATA Phy speed
78	F	044Ch	Serial ATA features supported
79	F	0040h	Serial ATA features enabled
80	F	0FF8h	Major Version Number
81	F	0000h	Minor Version Number
82	F	746Bh	Command set supported
83	F	7D09h	Command set supported
84	F	4163h	Command set/feature supported extension
85	F	7469h	Command set/feature supported or enabled
86	F	BC01h	Command set/feature supported or enabled
87	F	4163h	Command set/feature supported or enabled
88	F	007Fh	Ultra DMA Modes
89	F	000Ah	Time required for Normal Erase mode SECURITY ERASE UNIT command
90	F	001Eh	Time required for an Enhanced Erase mode SECURITY ERASE UNIT command
91	F	0000h	Current advanced power management value
92	F	FFFEh	Master Password Revision Code
Word	F: Fixed V: Variable X: retired/obsolete	Default Value	Description

	/reserved		
93	F	0000h	Hardware reset result. The contents of the bits (12:0) of this word can be changed only during the execution of hardware reset.
94	X	0000h	Vendor's recommended and actual acoustic management value
95	F	0000h	Stream Minimum Request Size
96	F	0000h	Streaming Transfer Time – DMA
97	F	0000h	Streaming Access Latency – DMA and PIO
98-99	F	00000000h	Streaming Performance Granularity
100-103	V	*4	Maximum user LBA for 48 bit Address feature set
104	F	0000h	Streaming Transfer Time – PIO
105	F	0004h	Maximum number of 512-byte blocks per DATA SET MANAGEMENT command
106	F	4000h	Physical sector size/Logical sector size
107	F	0000h	Inter-seek delay for ISO-7779 acoustic testing in microseconds
108-111	F	Varies	Reserved
112-115	X	0h	Reserved
116	X	0000h	Reserved
117-118	F	00000000h	Words per logical Sector
119	F	4018h	Supported settings
120	F	4018h	Command set/Feature Enabled/Supported
121-126	X	0h	Reserved
127	X	0000h	Obsolete
128	F	0021h	Security status
129-159	V	Varies	Vendor specific
160	X	0000h	Compact Flash Association (CFA) power mode 1
161-167	X	0h	Reserved for assignment by the CFA
168	V	Varies	Device Nominal Form Factor
169	F	0001h	DATA SET MANAGEMENT command is supported
170-173	F	0h	Additional Product Identifier
174-175	X	0h	Reserve
Word	F: Fixed V: Variable X: retired/obsolete /reserved	Default Value	Description
176-205	F	0h	Current media serial number

206	F	0000h	SCT Command Transport(
207-208	X	00000000h	Reserved
209	F	4000h	Alignment of logical blocks within a physical block
210-211	F	0000h	Write-Read-Verify Sector Count Mode 3 (not support)
212-213	F	0000h	Write-Read-Verify Sector Count Mode 2 (not support)
214-216	X	0000h	NV Cache relate (not support)
217	F	0001h	Non-rotating media device
218	X	0000h	Reserved
219	X	0000h	NV Cache relate (not support)
220	V	0000h	Write read verify feature set current mode
221	X	0000h	Reserved
222	F	107Fh	Transport major version number
223	F	0000h	Transport minor version number
224-229	X	0h	reserved
230-233	F	0h	Extend number of user addressable sectors
234	F	0001h	Minimum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h
235	F	FFFEh	Maximum number of 512-byte data blocks per DOWNLOAD MICROCODE command for mode 03h
236-242	X	0h	Reserved
243	X	0000h	Reserved
244-254	X	0h	Reserved
255	F	XXA5h XX is variable	Integrity word (Checksum and Signature)

▪ **List of Device Identification for Each Capacity**

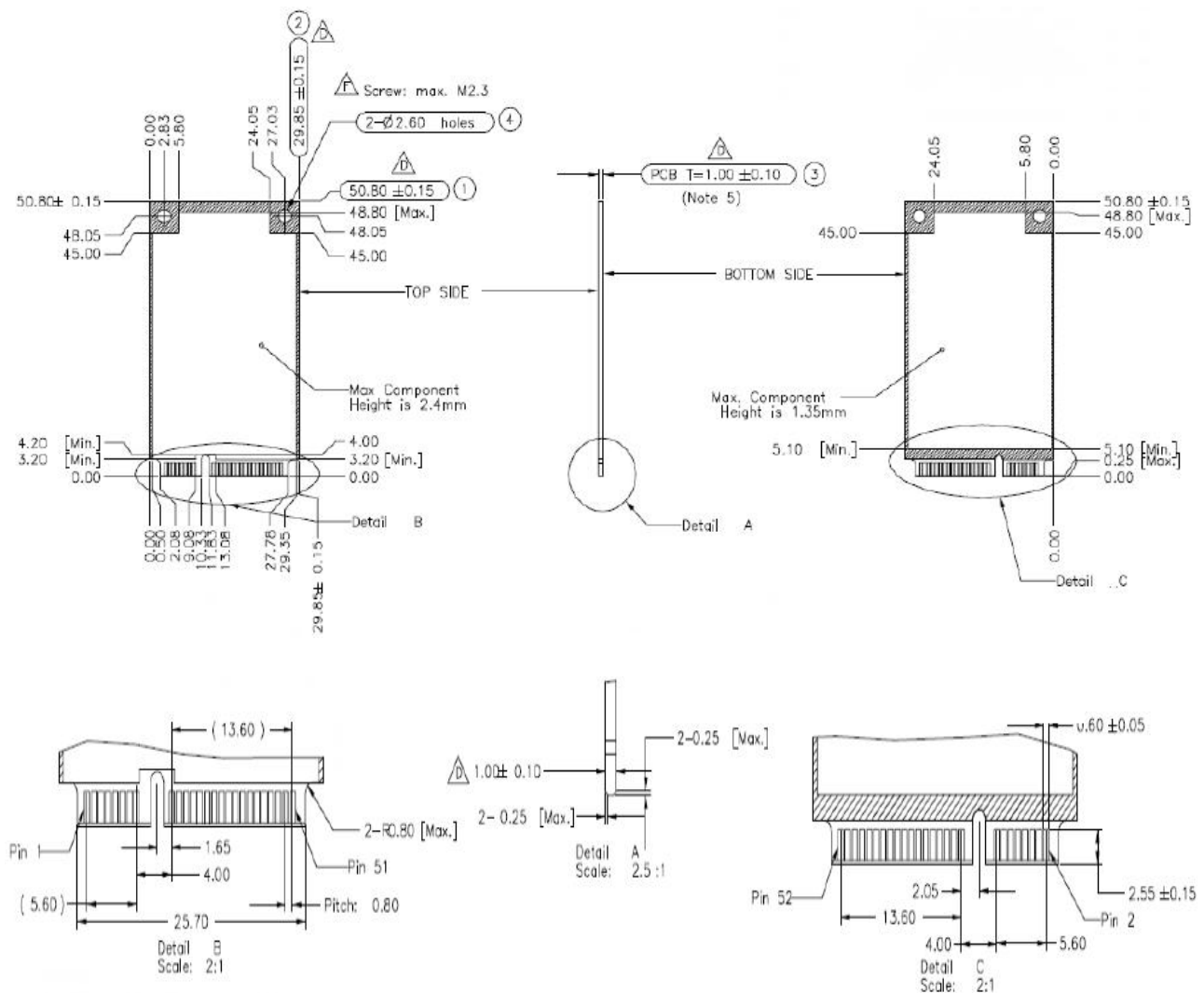
Capacity (GB)	*1 (Word 1/Word 54)	*2 (Word 57–58)	*3 (Word 60–61)	*4 (Word 100–103)
32	3FFFh	FBFC10h	3BA2EB0h	3BA2EB0h
60	3FFFh	FBFC10h	6FCCF30h	6FCCF30h
64	3FFFh	FBFC10h	7740AB0h	7740AB0h
120	3FFFh	FBFC10h	DF94BB0h	DF94BB0h
128	3FFFh	FBFC10h	EE7C2B0h	EE7C2B0h
240	3FFFh	FBFC10h	0FFFFFFFh	1BF244B0h
256	3FFFh	FBFC10h	0FFFFFFFh	1DCF32B0h
480	3FFFh	FBFC10h	0FFFFFFFh	37E436B0
512	3FFFh	FBFC10h	0FFFFFFFh	3B9E12B0h
960	3FFFh	FBFC10h	0FFFFFFFh	6FC81AB0h
1024	3FFFh	FBFC10h	0FFFFFFFh	773BD2B0h
1920	3FFFh	FBFC10h	0FFFFFFFh	DF8FE2B0h
2048	3FFFh	FBFC10h	0FFFFFFFh	EE7752B0h

6.3. S.M.A.R.T. Attributes

Entry	ID	Description
0	0x01	Number of Uncorrectable Errors Accumulated.
1	0x09	Power on Hours Count.
2	0x0C	Power Cycle Count (number of power on/off cycles accumulated)
3	0xA8	SATA PHY Error Count (Only record from power on, when power off this value will clear to zero. These values include all PHY error count, ex data FIS CRC, code error, disparity error, command FIS CRC.....)
4	0xAA	Bad Block Count (early bad count and later bad count)
5	0xAD	Erase Count (max. erase count and average erase count)
6	0xC0	Unexpected Power Loss Count
7	0xC2	Temperature (show 33°C if no thermal sensor)
8	0xDA	Number of Accumulation CRC Error (read/write data FIS CRC error)
9	0xE7	SSD Life Remaining
10	0xF1	Host Write (GB)

7. PHYSICAL DIMENSION

Dimension: 50.8mm(L) x 29.85mm(W) x 4mm(H)



Notes :

- Notes:
1.  = Max Component Height is
 2.  = No Component
 3.  = No Component / Signal Vias / Signal Copper/Print
 4. General Tolerance : $\pm 0.1\text{mm}$
 - △ 5. Card Thickness applies accross tab and includes plating and/or metalization
 - △ 6. Check Point: ① ~ ④
 - △ 7. Screw Max. Size M2.3

COMMON TOLERANCE				Finish		
DIM	CLASS	A	(B)	C	Material	
					Angles	
L≤3	±0.05	±0.10	±0.20	Scale : 1 / 1	Unit : mm	
3<L≤6	±0.05	±0.10	±0.20	Drawing by	Otto_Lian	
6<L≤16	±0.10	±0.15	±0.30	Approval	Tom	
16<L≤30	±0.10	±0.15	±0.30	Date	2014/11/03	
30<L≤120	±0.15	±0.20	±0.50	Size : A4	Rev.F	
120<L≤315	±0.20	±0.50	±0.80		Page 1/1	

8. TERMINOLOGY



The following table is to list out the acronyms that have been applied throughout the document.

Term	Definitions
ATTO	Commercial performance benchmark application
DDR	Double data rate (SDRAM)
DIPM	Device initiated power management
HIPM	Host initiated power management
LBA	Logical block addressing
MB	Mega-byte
MTBF	Mean time between failures
NCQ	Native command queue
SATA	Serial advanced technology attachment
S.M.A.R.T.	Self-monitoring, analysis and reporting technology
SSD	Solid state disk

9. BARCODE DESCRIPTION



